Pb Free Product

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3060G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =30V,I_D =60A

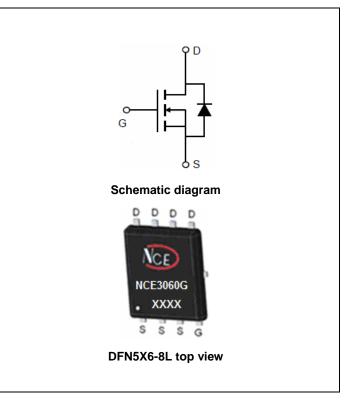
 $R_{DS(ON)}$ <4.0 m Ω @ V_{GS} =10V

 $R_{DS(ON)}$ <5.5 m Ω @ V_{GS} =4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3060G	NCE3060G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	60	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	47	Α
Pulsed Drain Current	I _{DM}	200	А
Maximum Power Dissipation	P _D	60	W
Derating factor		0.5	W/℃
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{ heta JC}$	2.0	°C/W



NCE3060G

Electrical Characteristics (T_C=25 [°]C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	35	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.5	2.0	V
Drain Course On State Registeres	В	V _{GS} =10V, I _D =20A	-	3.2	4.0	m0
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A		3.4	5.5	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	-	70	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V,	-	2850	-	PF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	407	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0WHZ	-	327	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, R_L =15 Ω	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =2.5 Ω	-	42	-	nS
Turn-Off Fall Time	t _f		-	14	-	nS
Total Gate Charge	Qg	\/ -45\/ L -20A	-	69		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =20A,	-	7.4		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	16.4		nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	60	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	26	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	34	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+L				y LS+LD)

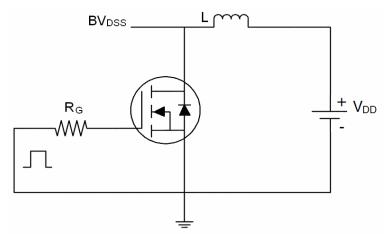
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

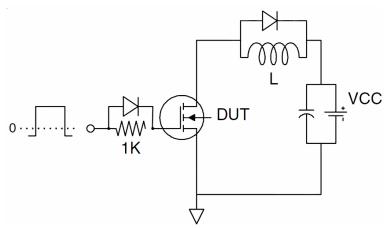
Test circuit

1) E_{AS} Test Circuit

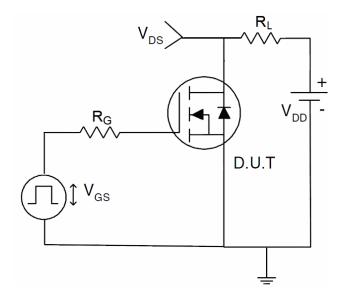




2) Gate Charge Test Circuit



3) Switch Time Test Circuit







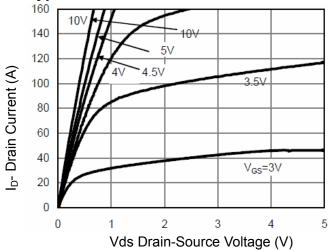


Figure 1 Output Characteristics

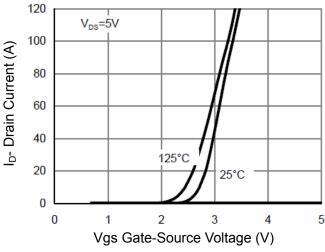


Figure 2 Transfer Characteristics

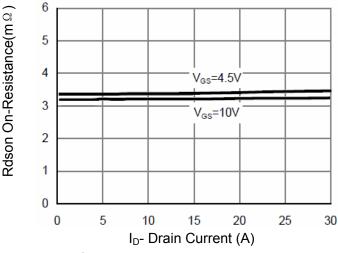


Figure 3 Rdson- Drain Current

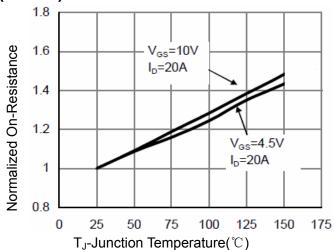


Figure 4 Rdson-JunctionTemperature

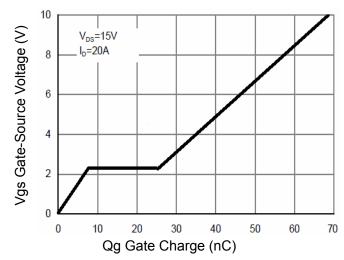


Figure 5 Gate Charge

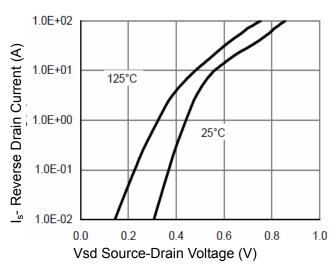


Figure 6 Source- Drain Diode Forward



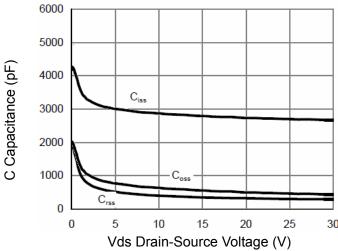


Figure 7 Capacitance vs Vds

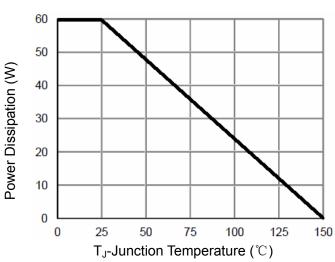


Figure 9 Power De-rating

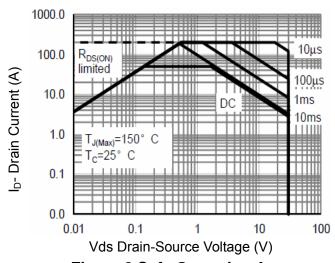


Figure 8 Safe Operation Area

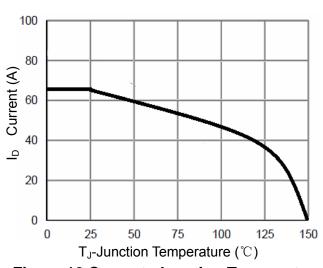


Figure 10 Current- Junction Temperature

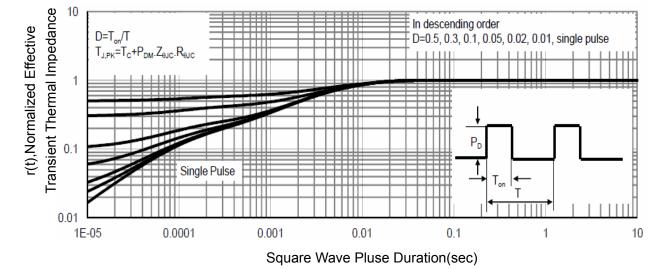
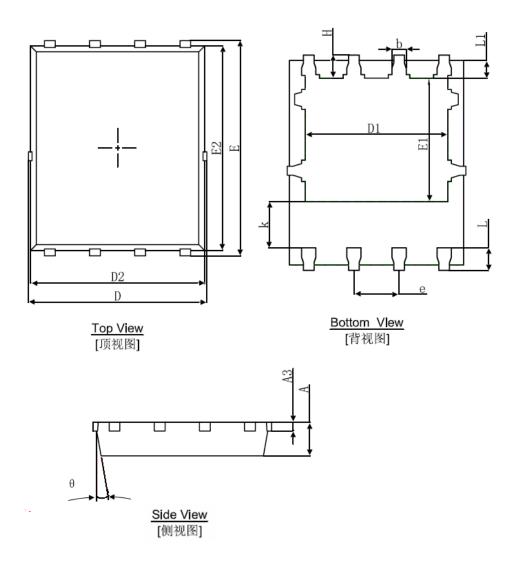


Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



C) male al	Dimensions I	n Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
Α	0.900	1.000	0.035	0.039		
A3	0.254	REF.	0.010	IOREF.		
D	4.944	5.096	0.195	0.201		
E	5.974	6.126	0.235	0.241		
D1	3.910	4.110	0.154	0.162		
E1	3.375	3.575	0.133	0.141		
D2	4.824	4.976	0.190	0.196		
E2	5.674	5.826	0.223	0.229		
k	1.190	1.390	0.047	0.055		
b	0.350	0.450	0.014	0.018		
е	1.270TYP.		0.050	TYP.		
L	0.559	0.711	0.022	0.028		
L1	0.424	0.576	0.017	0.023		
Н	0.574	0.726	0.023	0.029		
θ	8°	12°	8°	12°		



http://www.ncepower.com

NCE3060G

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